



COPY OF PERS
ORIGINAL FILED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#3/Revoc P/A
11/1/02 2818
C. Moore

Applicant: Cheng-Yi Liu et al.

Title: Thinned Die Integrated Circuit Package

Docket No.: 884.793US1

Serial No.: 10/036,389

Filed: January 7, 2002

Due Date: N/A

Examiner: Unknown

Group Art Unit: Unknown

Commissioner for Patents

Washington, D.C. 20231

RECEIVED
SEP 17 2002
TECHNOLOGY CENTER 2800

We are transmitting herewith the attached:

Revocation and Power of Attorney (2 pages)

A return postcard.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Ann M. McCrackin

Name: Ann M. McCrackin

Reg. No. 42,858

AMM1:jeb1

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 3 day of September, 2002.

Jane E. Brockschink

Name

Jane Brockschink

Signature